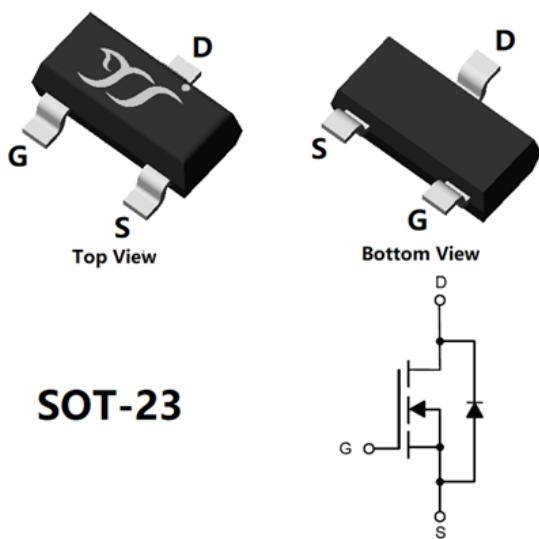


N-Channel Enhancement Mode Field Effect Transistor



Product Summary

- V_{DS} 100V
- I_D 3A
- $R_{DS(ON)}$ (at $V_{GS}=10V$) <140 mohm
- $R_{DS(ON)}$ (at $V_{GS}=4.5V$) <300 mohm

General Description

- Split Gate Trench MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low $R_{DS(ON)}$
- Moisture Sensitivity Level 1
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free

Applications

- DC-DC Converters
- Power management functions

■ Absolute Maximum Ratings ($T_A=25^\circ C$ unless otherwise noted)

| Parameter | Symbol | Limit | Unit |
|--|----------------|----------|------|
| Drain-source Voltage | V_{DS} | 100 | V |
| Gate-source Voltage | V_{GS} | ± 20 | V |
| Drain Current | I_D | 3 | A |
| | | 2.4 | |
| Pulsed Drain Current ^A | I_{DM} | 12 | A |
| Avalanche energy ^B | E_{AS} | 1.3 | mJ |
| Total Power Dissipation ^C | P_D | 1.2 | W |
| | | 0.8 | |
| Junction and Storage Temperature Range | T_J, T_{STG} | -55~+150 | °C |

■ Thermal resistance

| Parameter | Symbol | Typ | Max | Units |
|---|-----------------|-----|-----|-------|
| Thermal Resistance Junction-to-Ambient ^D | $R_{\theta JA}$ | 82 | 104 | °C/W |
| Thermal Resistance Junction-to-Ambient ^{D E} | | 111 | 140 | |
| Thermal Resistance Junction-to-Case | $R_{\theta JL}$ | 43 | 52 | |

■ Ordering Information (Example)

| PREFERRED P/N | PACKING CODE | Marking | MINIMUM PACKAGE(pcs) | INNER BOX QUANTITY(pcs) | OUTER CARTON QUANTITY(pcs) | DELIVERY MODE |
|---------------|--------------|---------|----------------------|-------------------------|----------------------------|---------------|
| YJL03G10A | F2 | 1003. | 3000 | 30000 | 120000 | 7"Reel |



YJL03G10A

■ Electrical Characteristics ($T_j=25^\circ\text{C}$ unless otherwise noted)

| Parameter | Symbol | Conditions | Min | Typ | Max | Units |
|---------------------------------------|--------------------------|--|-----|------|-----------|------------------|
| Static Parameter | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{\text{GS}} = 0\text{V}, I_{\text{D}} = 250\mu\text{A}$ | 100 | | | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{\text{DS}} = 100\text{V}, V_{\text{GS}} = 0\text{V}$ | | | 1 | μA |
| Gate-Body Leakage Current | I_{GSS} | $V_{\text{GS}} = \pm 20\text{V}, V_{\text{DS}} = 0\text{V}$ | | | ± 100 | nA |
| Gate Threshold Voltage | $V_{\text{GS(th)}}$ | $V_{\text{DS}} = V_{\text{GS}}, I_{\text{D}} = 250\mu\text{A}$ | 1.0 | 1.8 | 2.5 | V |
| Static Drain-Source On-Resistance | $R_{\text{DS(ON)}}$ | $V_{\text{GS}} = 10\text{V}, I_{\text{D}} = 3\text{A}$ | | 110 | 140 | $\text{m}\Omega$ |
| | | $V_{\text{GS}} = 4.5\text{V}, I_{\text{D}} = 2\text{A}$ | | 160 | 300 | $\text{m}\Omega$ |
| Diode Forward Voltage | V_{SD} | $I_{\text{S}} = 3\text{A}, V_{\text{GS}} = 0\text{V}$ | | | 1.3 | V |
| Maximum Body-Diode Continuous Current | I_{S} | | | | 3 | A |
| Gate resistance | R_{G} | $f = 1 \text{ MHz}$ | | 8 | | Ω |
| Dynamic Parameters | | | | | | |
| Input Capacitance | C_{iss} | $V_{\text{DS}} = 50\text{V}, V_{\text{GS}} = 0\text{V}, f = 100\text{KHZ}$ | | 206 | | pF |
| Output Capacitance | C_{oss} | | | 28.9 | | |
| Reverse Transfer Capacitance | C_{rss} | | | 1.4 | | |
| Switching Parameters | | | | | | |
| Total Gate Charge | Q_{g} | $V_{\text{GS}} = 10\text{V}, V_{\text{DS}} = 50\text{V}, I_{\text{D}} = 3\text{A}$ | | 4.3 | | nC |
| Gate-Source Charge | Q_{gs} | | | 1.5 | | |
| Gate-Drain Charge | Q_{gd} | | | 1.1 | | |
| Reverse Recovery Charge | Q_{rr} | $I_{\text{f}} = 3\text{A}, \frac{dI}{dt} = 100\text{A/us}$ | | 39.4 | | ns |
| Reverse Recovery Time | t_{rr} | | | 32.1 | | |
| Turn-on Delay Time | $t_{\text{D(on)}}$ | $V_{\text{GS}} = 10\text{V}, V_{\text{DD}} = 50\text{V}, I_{\text{D}} = 3\text{A}$ $R_{\text{GEN}} = 2\Omega$ | | 14.7 | | ns |
| Turn-on Rise Time | t_{r} | | | 3.5 | | |
| Turn-off Delay Time | $t_{\text{D(off)}}$ | | | 20.9 | | |
| Turn-off fall Time | t_{f} | | | 2.7 | | |

- A. Repetitive rating; pulse width limited by max. junction temperature.
- B. $V_{\text{DD}} = 50\text{V}$, $R_{\text{G}} = 25\Omega$, $L = 0.5\text{mH}$.
- C. P_{d} is based on max. junction temperature, using $\leq 10\text{us}$ junction-to-ambient thermal resistance.
- D. The value of $R_{\theta_{\text{JA}}}$ is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$. The value in any given application depends on the user's specific board design.
- E. The $R_{\theta_{\text{JA}}}$ is the sum of the thermal impedance from junction to lead $R_{\theta_{\text{JL}}}$ and lead to ambient



■ Typical Performance Characteristics

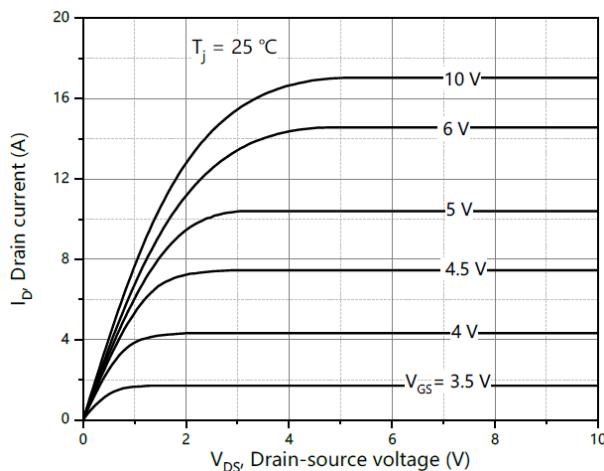


Figure1. Output Characteristics

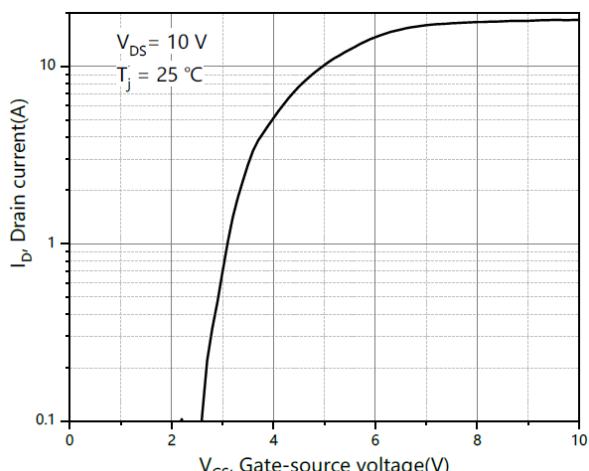


Figure2. Transfer Characteristics

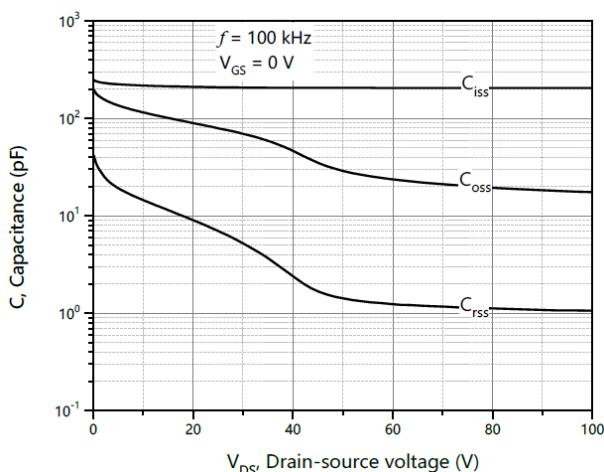


Figure3. Capacitance Characteristics

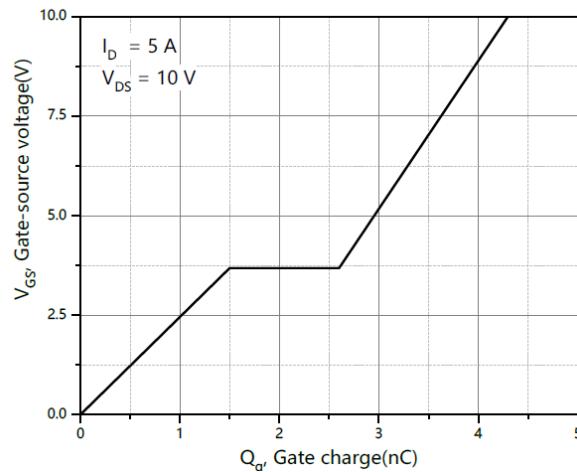


Figure4. Gate Charge

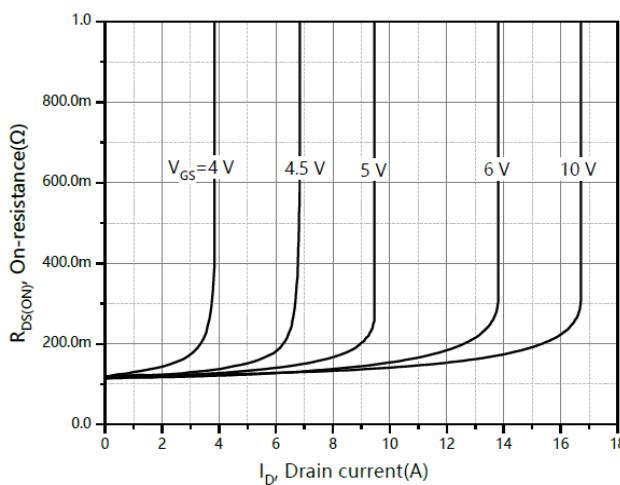


Figure5. : On-Resistance vs. Drain Current and Gate Voltage

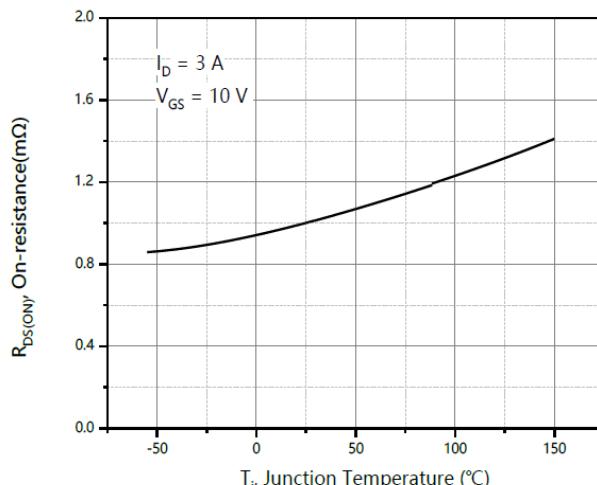


Figure6. Normalized On-Resistance

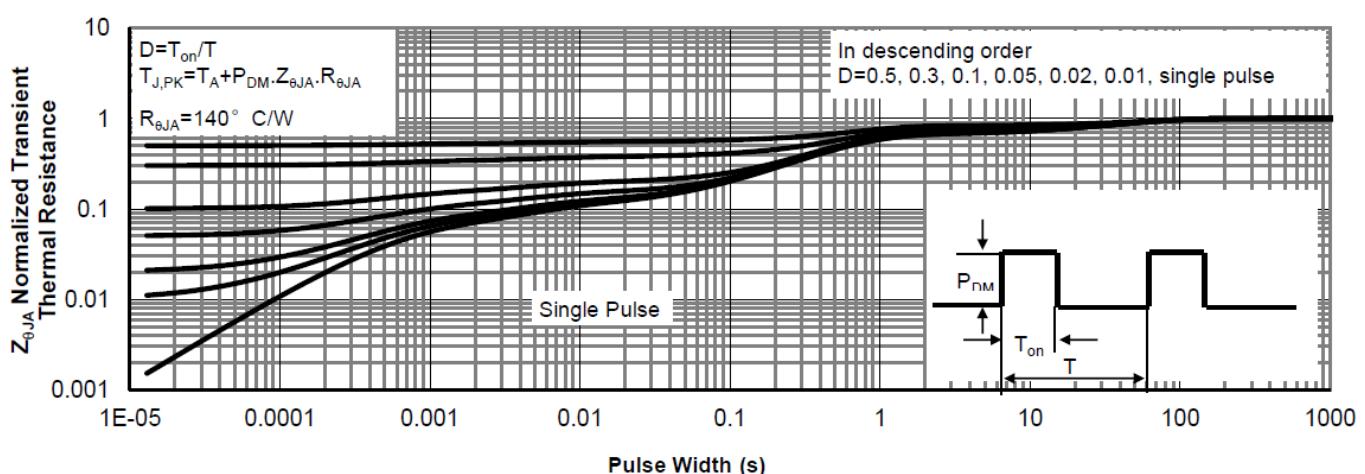
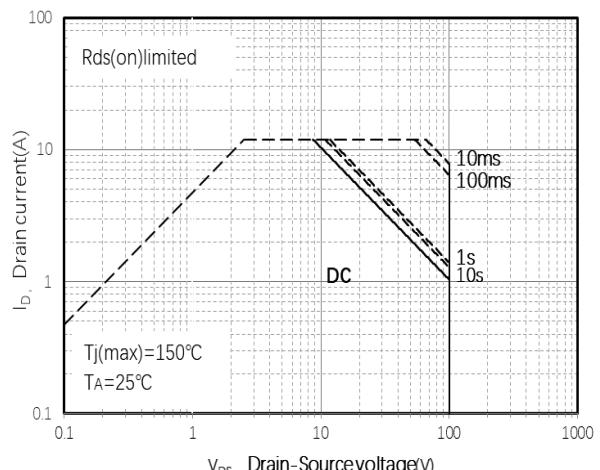
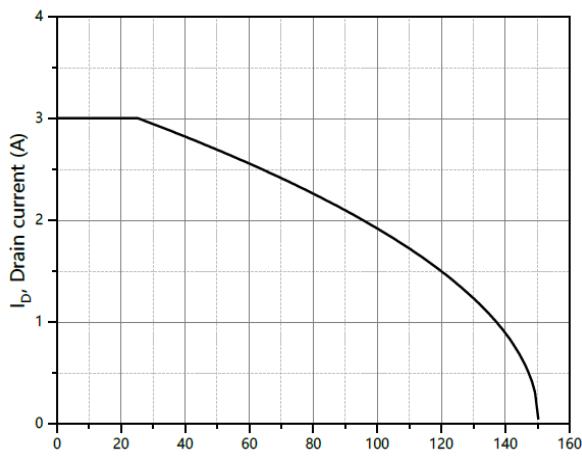


Figure 9. Normalized Maximum Transient thermal impedance

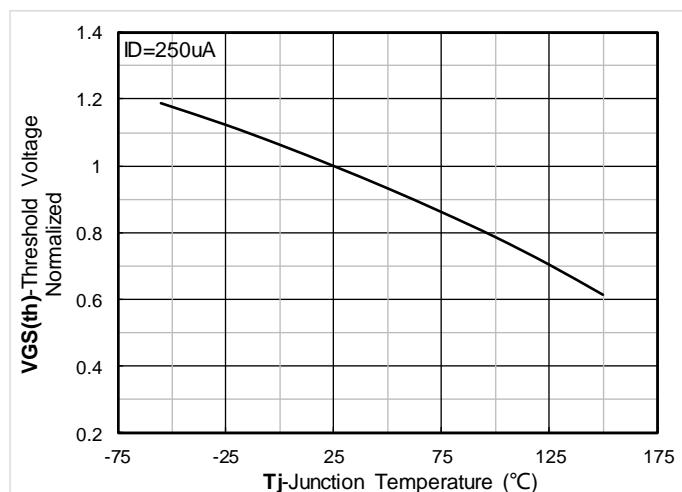
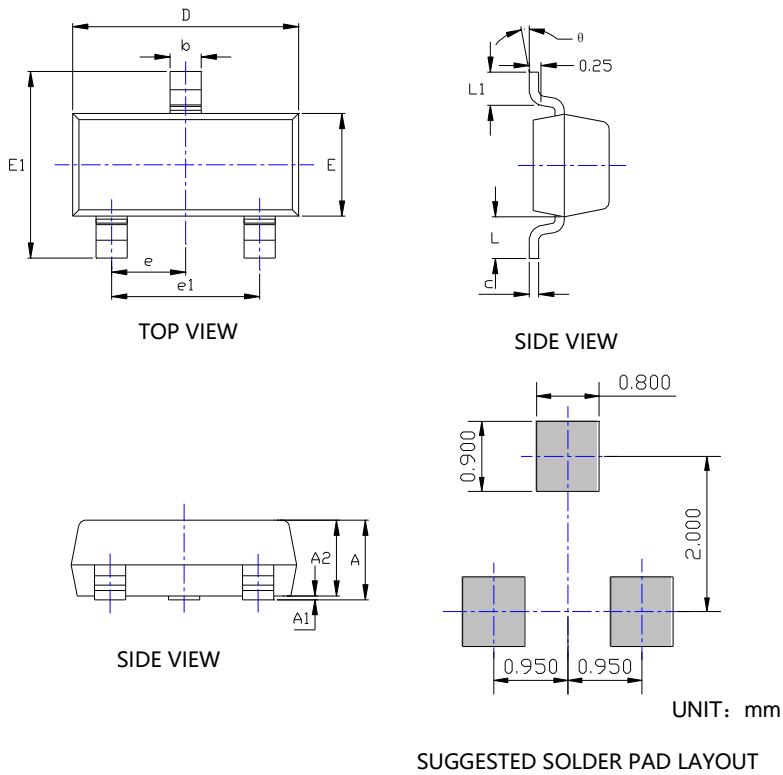


Figure 10. Normalized Threshold voltage

**■ SOT-23 Package information**

| SYMBOL | INCHES | | Millimeter | |
|--------|----------|-------|------------|-------|
| | MIN. | MAX. | MIN. | MAX. |
| A | 0.035 | 0.045 | 0.900 | 1.150 |
| A1 | 0.000 | 0.004 | 0.000 | 0.100 |
| A2 | 0.035 | 0.041 | 0.900 | 1.050 |
| b | 0.012 | 0.020 | 0.300 | 0.500 |
| c | 0.004 | 0.008 | 0.100 | 0.200 |
| D | 0.110 | 0.118 | 2.800 | 3.000 |
| E | 0.047 | 0.055 | 1.200 | 1.400 |
| E1 | 0.089 | 0.100 | 2.250 | 2.550 |
| e | 0.037TYP | | 0.950TYP | |
| e1 | 0.071 | 0.079 | 1.800 | 2.000 |
| L | 0.022REF | | 0.550REF | |
| L1 | 0.012 | 0.200 | 0.300 | 0.500 |
| theta | 0° | 8° | 0° | 8° |

NOTE:

- 1.PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
- 2.TOLERANCE 0.1mm UNLESS OTHERWISE SPECIFIED.
- 3.THE PAD LAYOUT IS FOR REFERENCE PURPOSES ONLY.



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